



SW Test Workshop
Semiconductor Wafer Test Workshop

Optimization for Polyimide Circuit Design of Space Transformer on Probe Card



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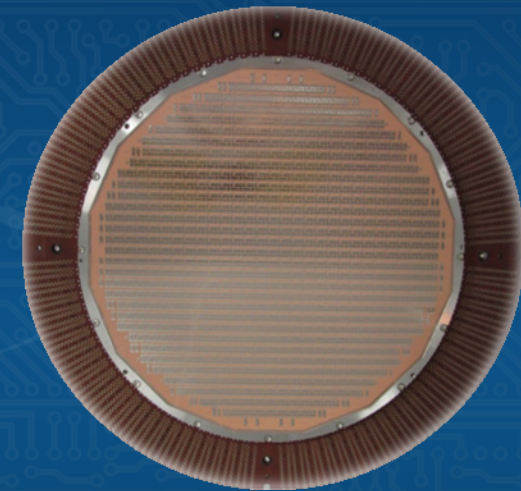
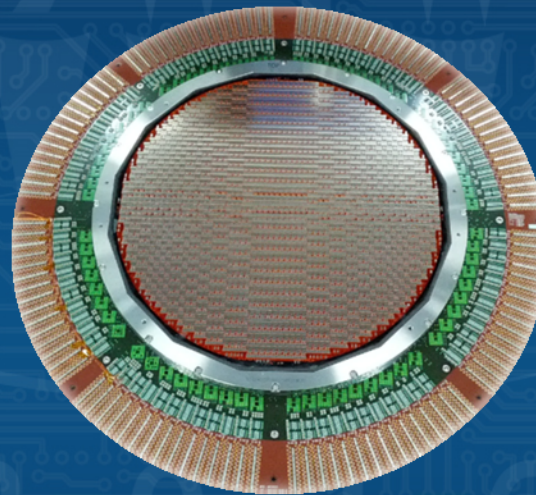
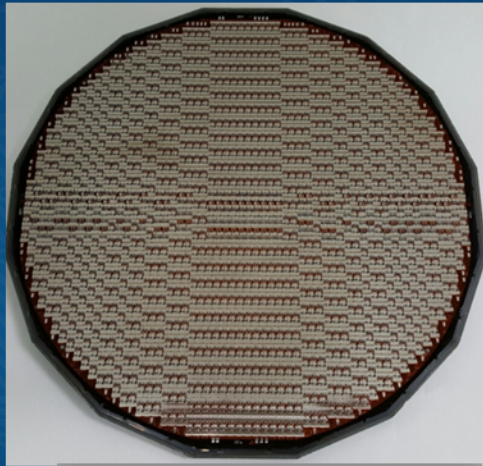
June 5-8, 2016

Overview

- **Introduction of Probe Card Test**
- **Basic Study for Polyimide Circuit Design**
- **Signal Integrity on Probe Card**
- **Summary**
- **Future Works**

Introduction of Probe Card Test

- Probe Card needs for High Parallel, High Speed and High Density.

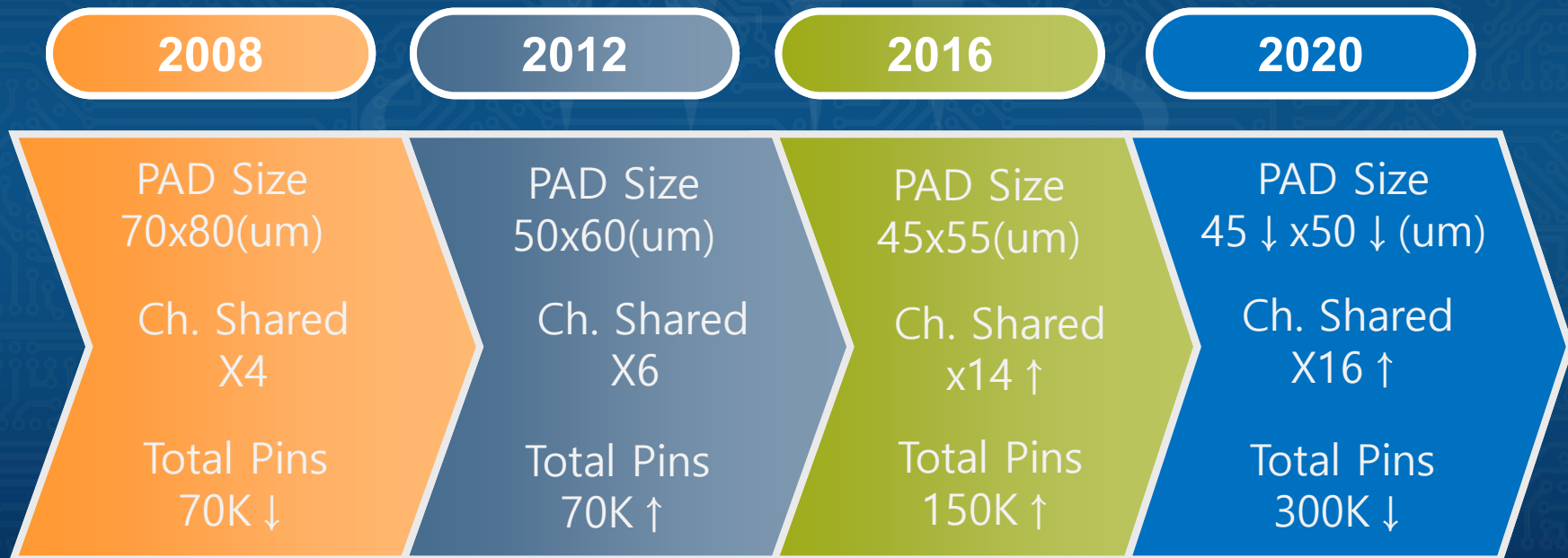


- Probe Card has a Function of Interface between ATE and Device.
- As Test Channels are Increase, Signal Integrity is getting more Important.
- It is necessary for High Parallel, High Density and High Speed on Probe Card.

Introduction of Probe Card Test

- **Test Trends**

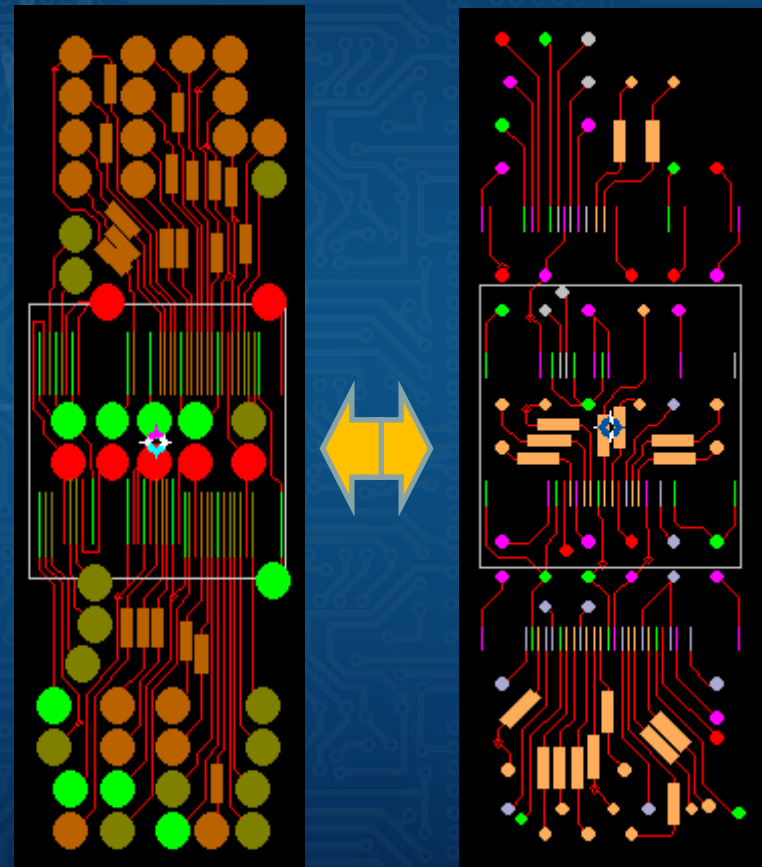
- Smaller PAD Size & Fine Pitch and Higher Pin Counts
- Necessity of High Speed Testing Technology on Probe Card
- Higher Circuit Design Density



Introduction of Probe Card Test

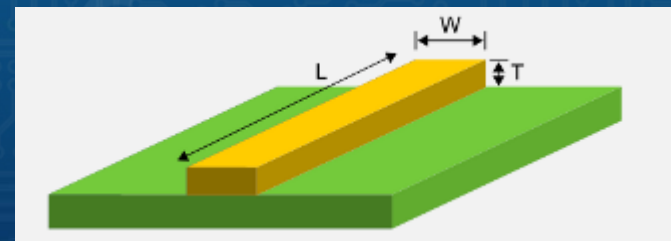
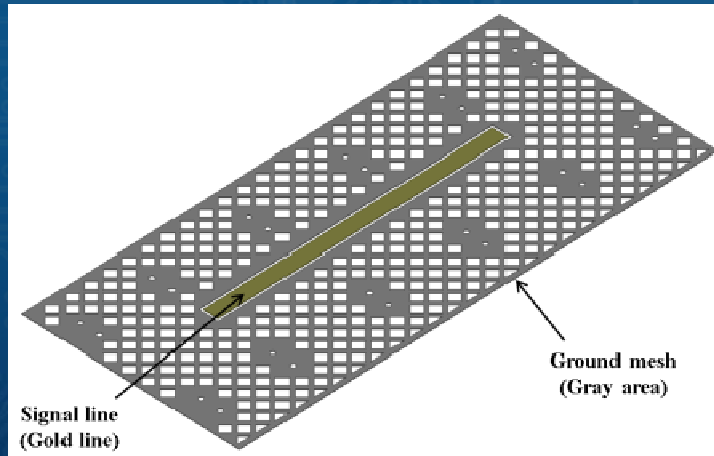
- **Advantage of Polyimide Thin Film**

- Very Small VIA Hole
- Highly Denser Circuit
- Low Relative Dielectric Constant
- High Propagation Velocity
- High Speed Digital Circuits
- Low Cost



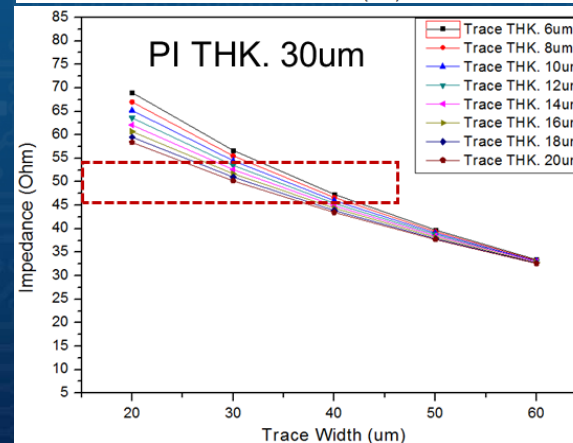
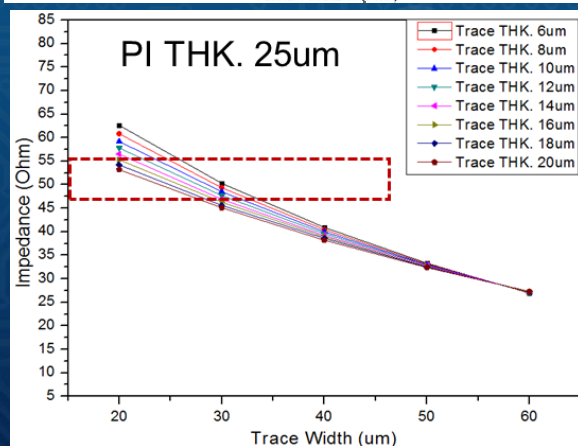
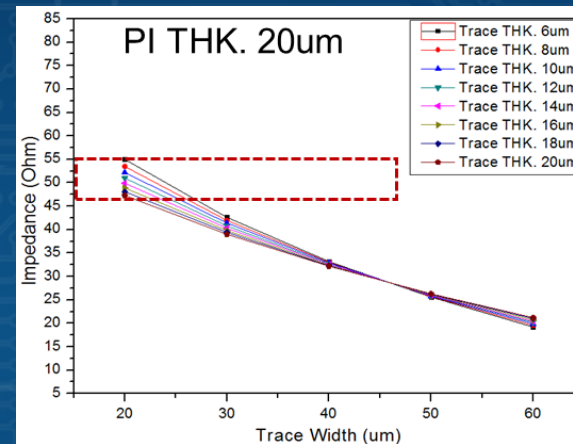
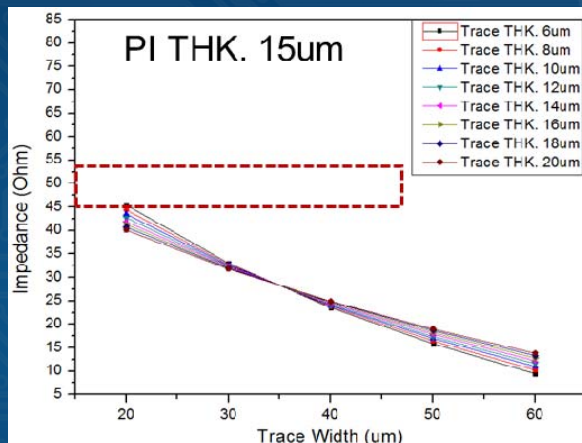
Basic Study for PI Circuit Design

- Needs for Electrical Characteristics of Circuit Trace in Polyimide Thin Film
 - Dielectric Constant : 3.2
 - Impedance depends on Trace THK., Width, Material, Ground(Mesh & Plane)



Basic Study for PI Circuit Design

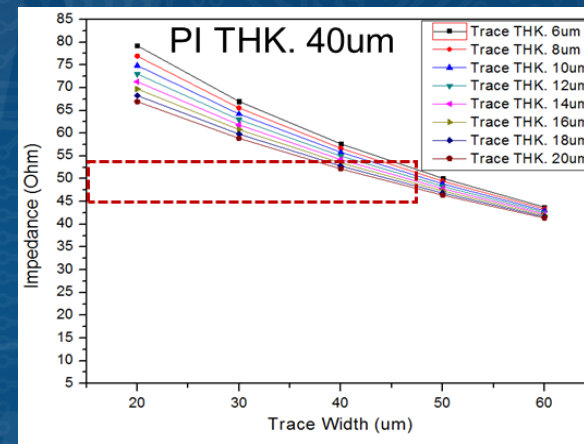
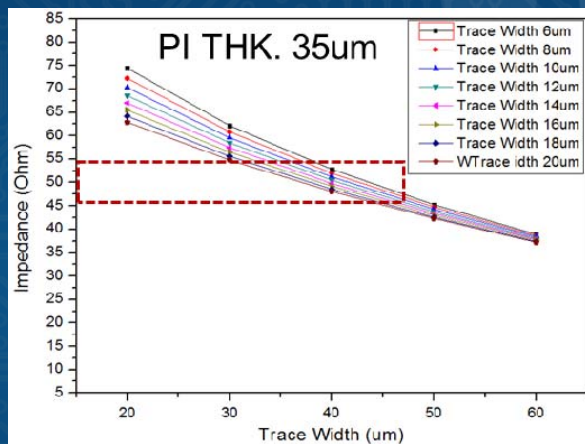
- Impedance depends on Circuit Trace Width & Thickness and PI Thickness.



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Basic Study for PI Circuit Design

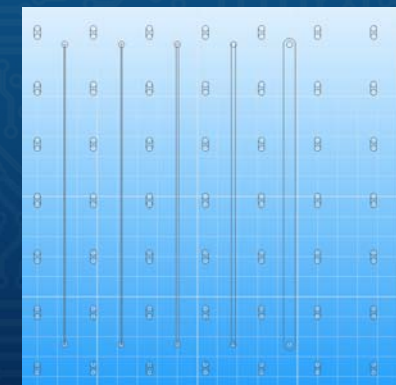
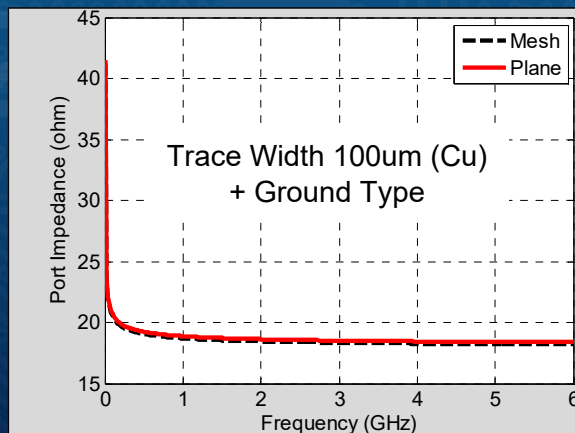
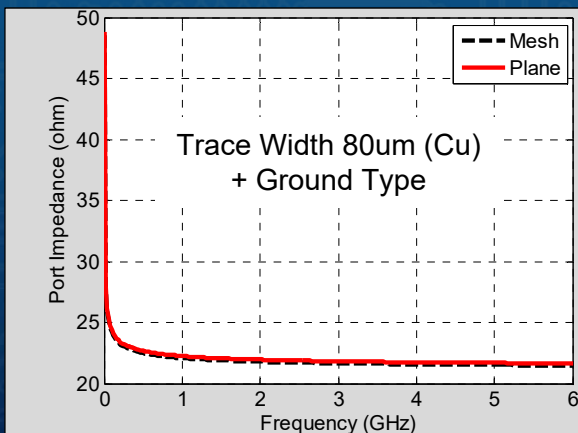
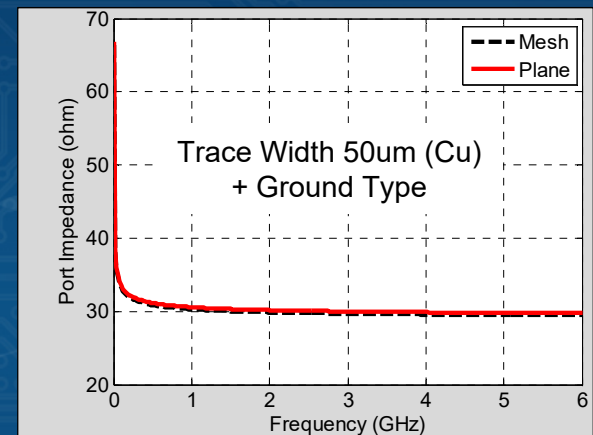
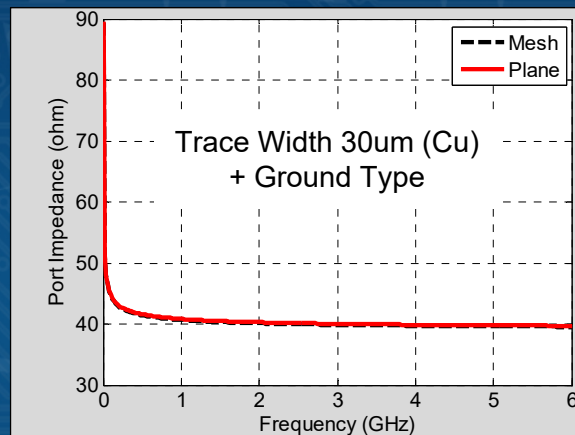
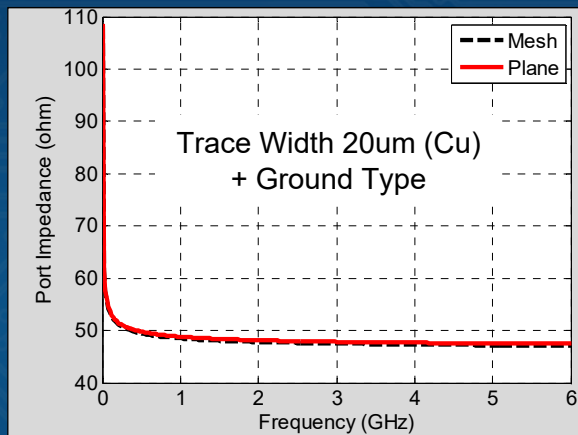
- Impedance depends on Circuit Trace Width & Thickness and PI Thickness.



- **Circuit Design on Polyimide Thin Film**
 - Normally, Target Impedance needs for $50 \pm 10\%$ Ohm.
 - Impedance mismatching affects poor Signal Quality.

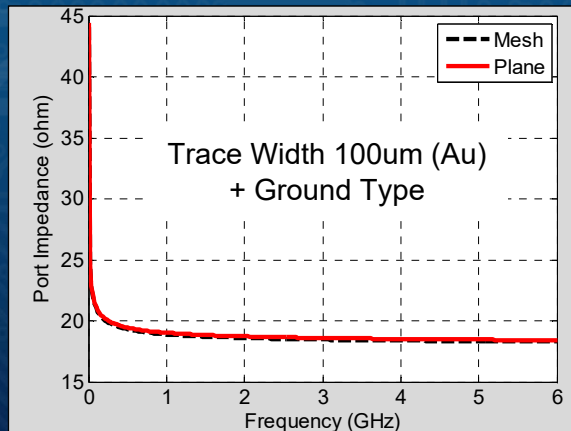
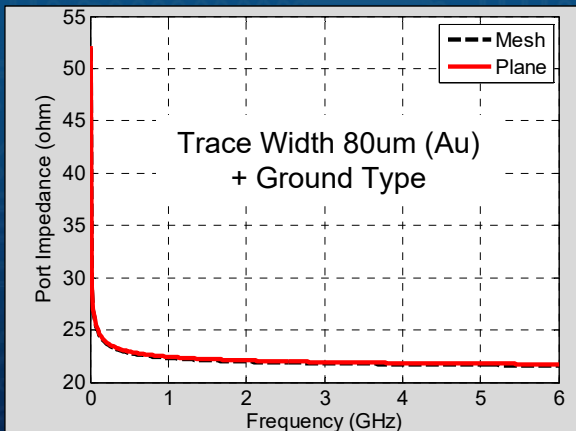
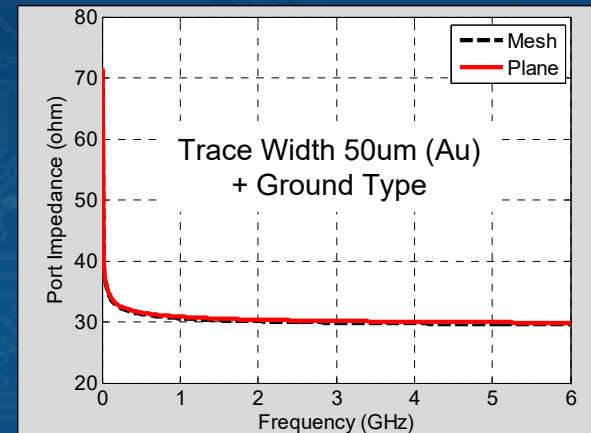
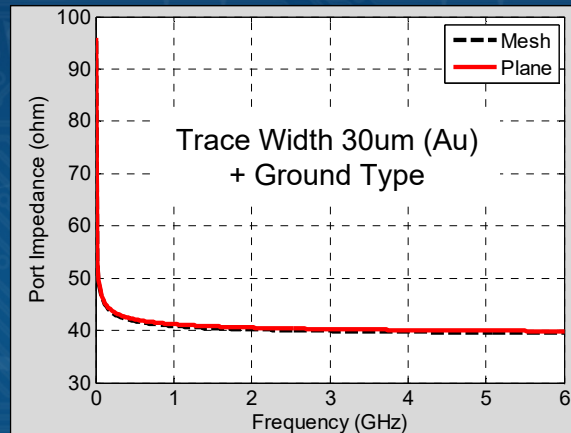
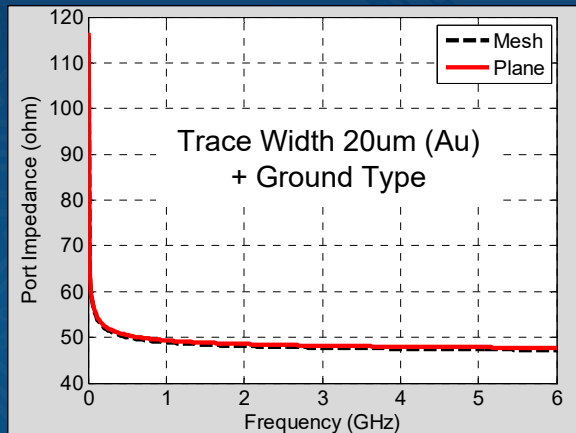
Basic Study for PI Circuit Design

- Analysis of Impedance for Trace Material (Cu), Width and Ground Type (Mesh or Plane)



Basic Study for PI Circuit Design

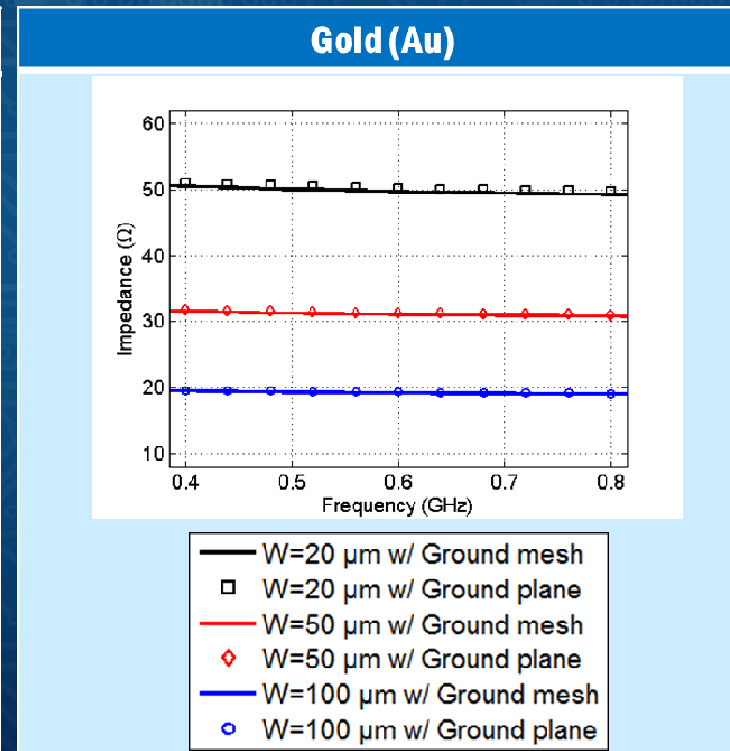
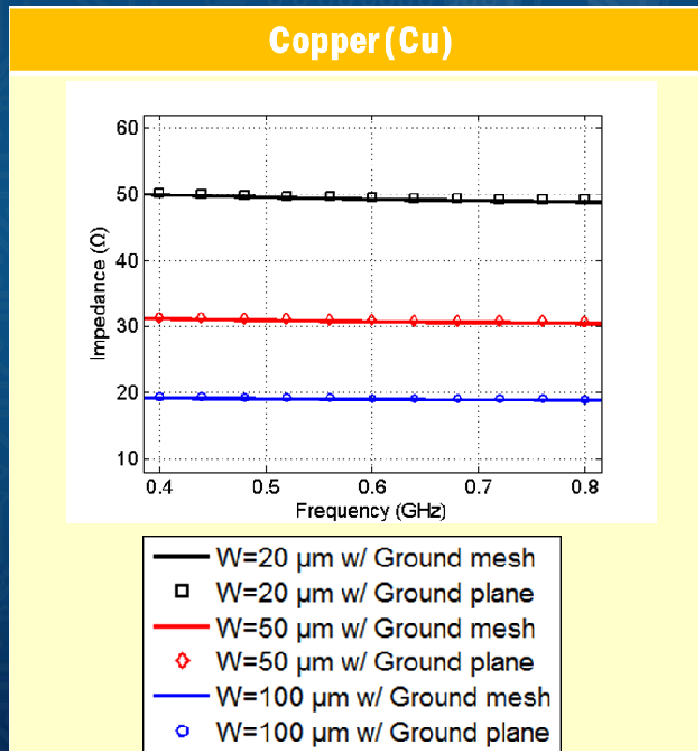
- Analysis of Impedance for Trace Material (Au), Width and Ground Type (Mesh or Plane)



Basic Study for PI Circuit Design

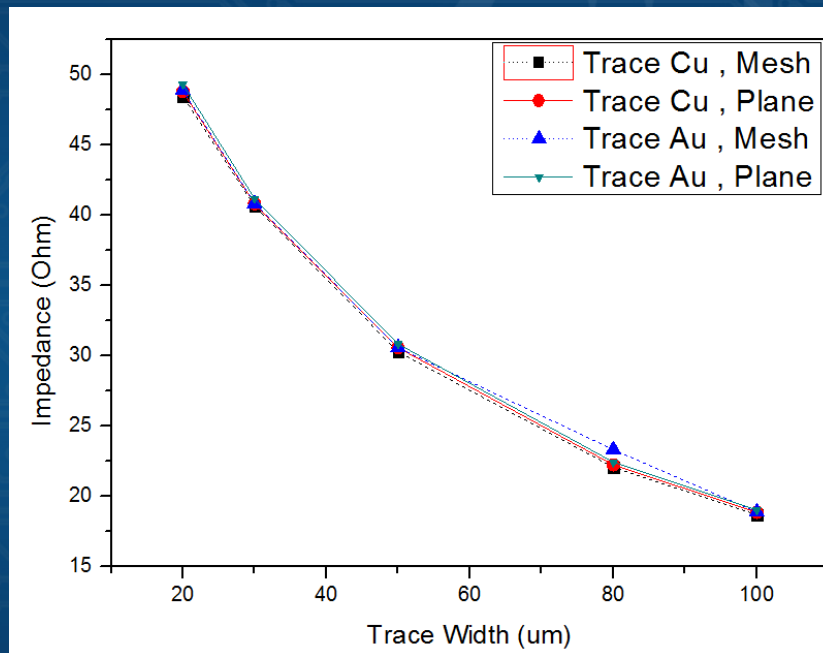
- **Analysis of Impedance for Circuit Trace**

- Depends on Circuit Material, Width and Ground Type
- Copper (Cu) vs Gold (Au)



Basic Study for PI Circuit Design

- Impedance Compared of Copper (Cu) with Gold (Au)



Resistivity

Copper (Cu)

: $1.68 \times 10^{-8} \Omega\text{m}$

Gold (Au)

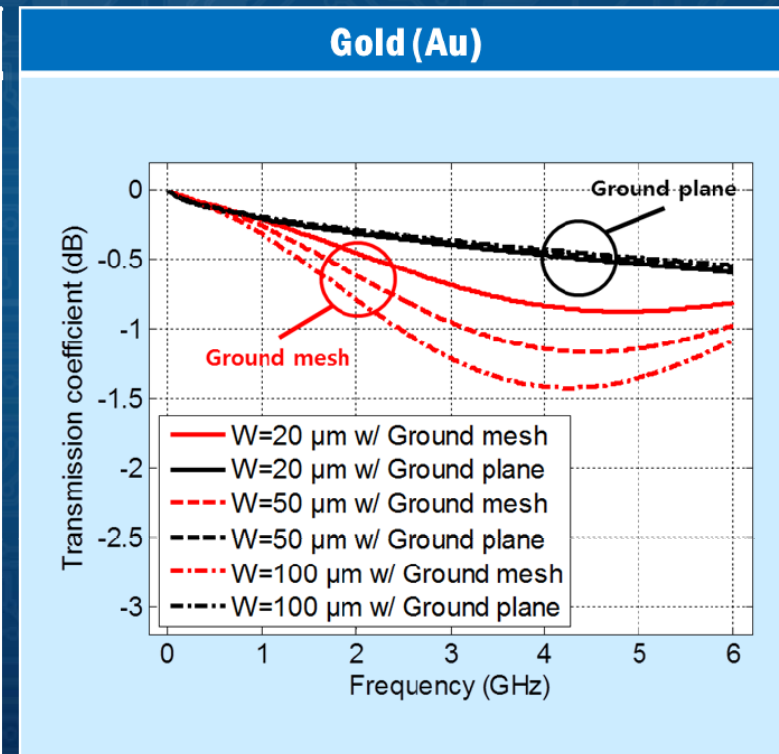
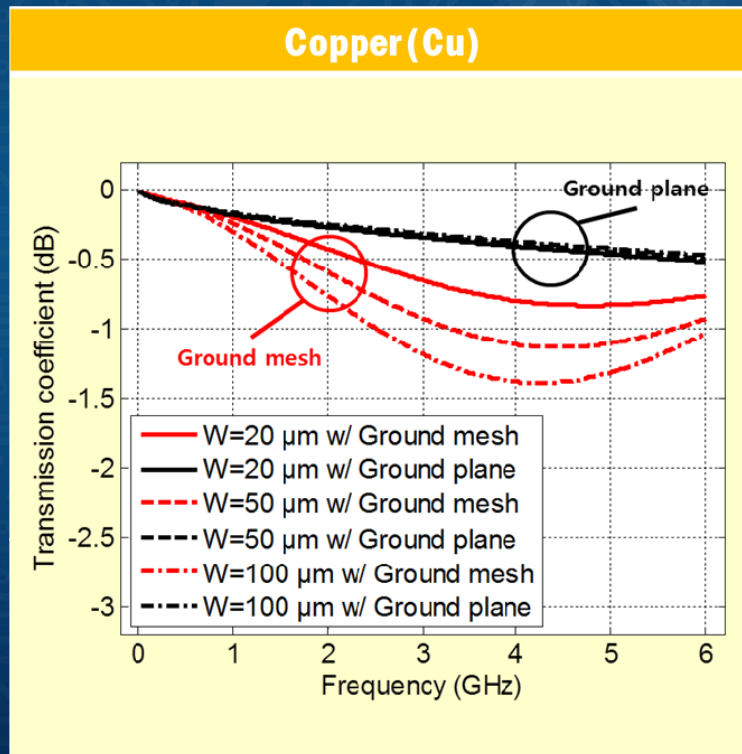
: $2.2 \times 10^{-8} \Omega\text{m}$

- Copper (Cu) vs Gold (Au) , Mesh Ground vs Plane Ground

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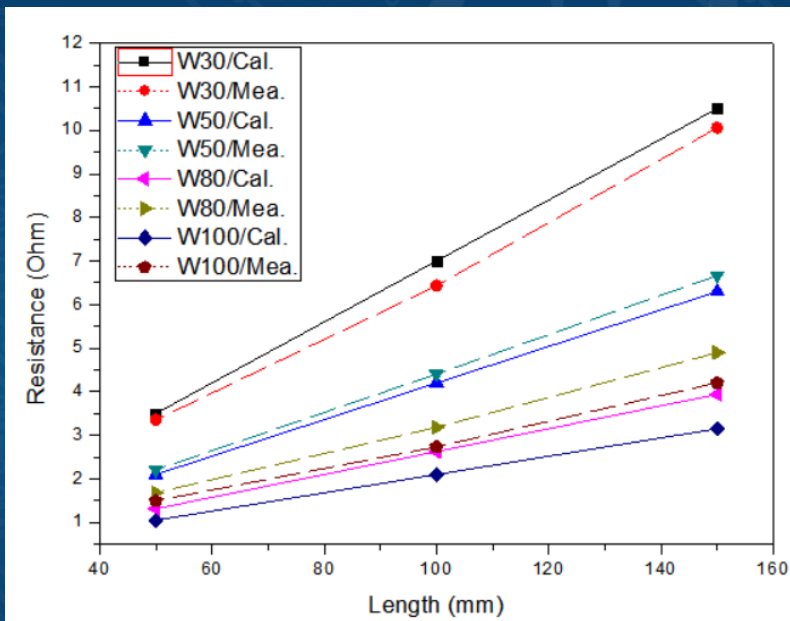
Basic Study for PI Circuit Design

- **Insertion Loss (Transmission coefficient)**
 - Depends on Circuit Material, Width and Ground type(Mesh & Plane)
 - Mesh Ground Insertion Loss Max. -1.5dB @ 4GHz

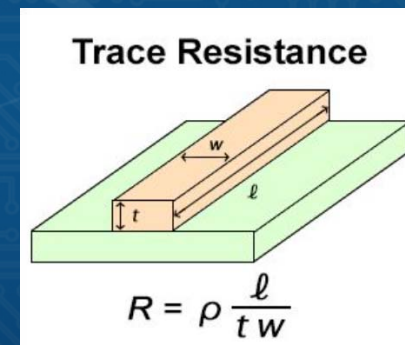


Basic Study for PI Circuit Design

- Measurement vs Calculation (Trace)



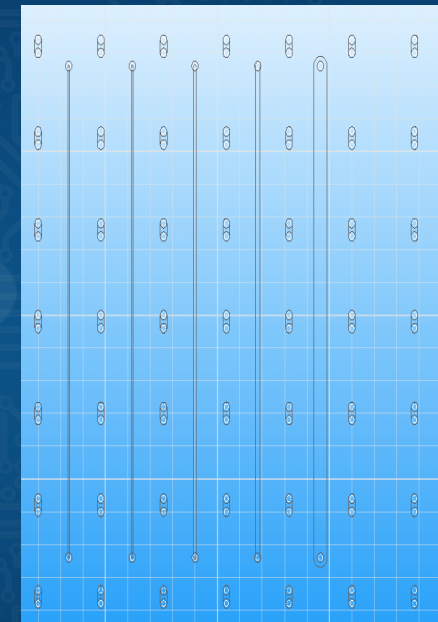
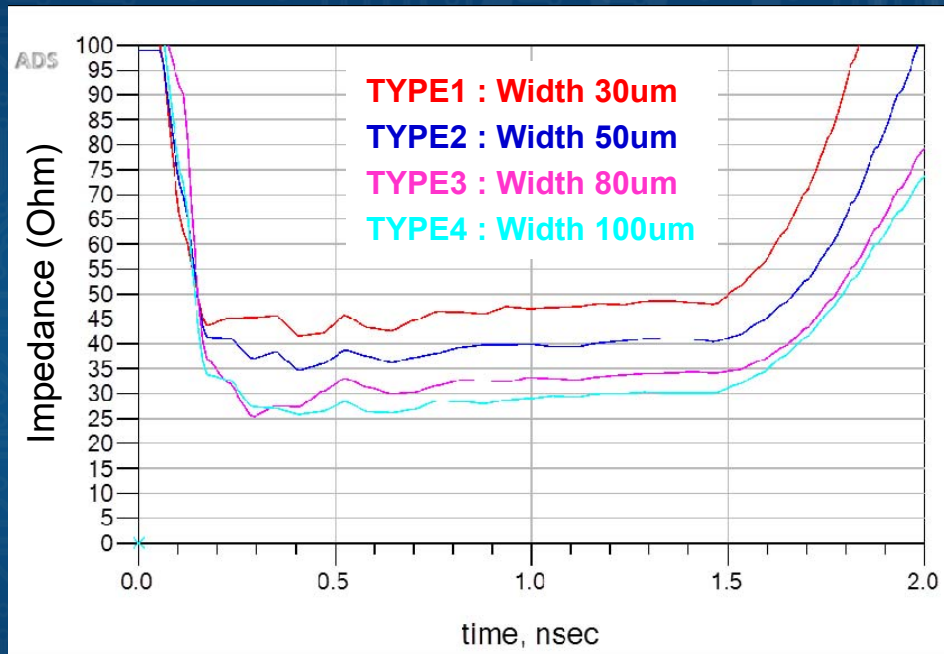
Copper Resistivity
 $1.68 \times 10^{-8} \Omega\text{m}$



- As Trace Length is Large, the Resistance is getting Higher.
- As Trace Width is Large, the Resistance is getting Lower.

Basic Study for PI Circuit Design

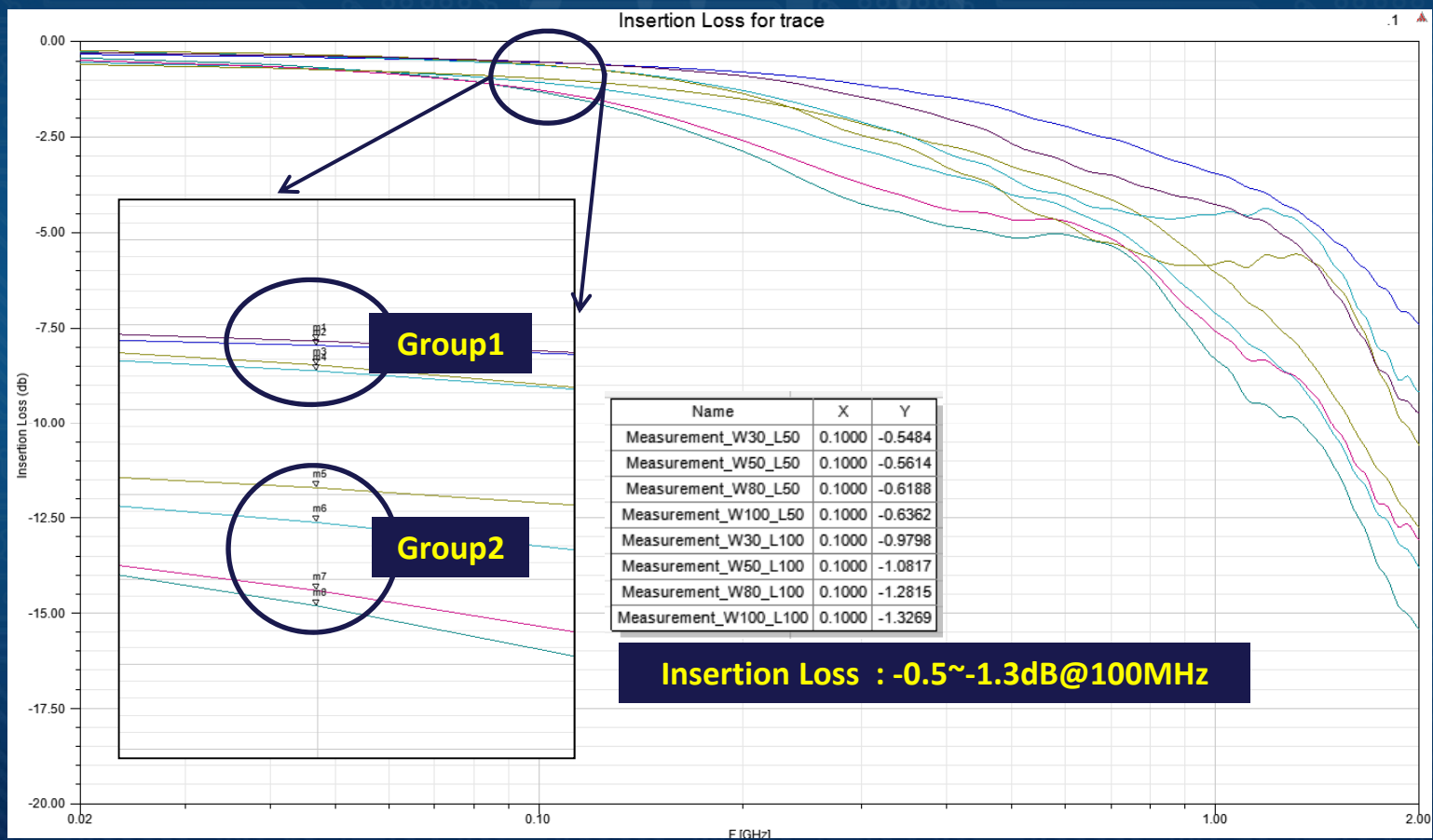
- **Measurement (Impedance)**



- As Trace Width is Small, the Impedance is getting Higher.
- Measurement shows impedance for Circuit Trace Width.

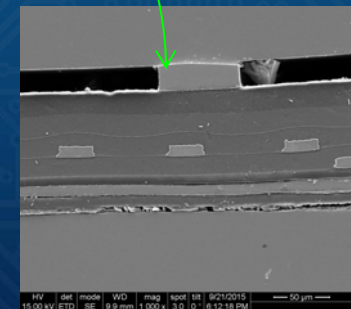
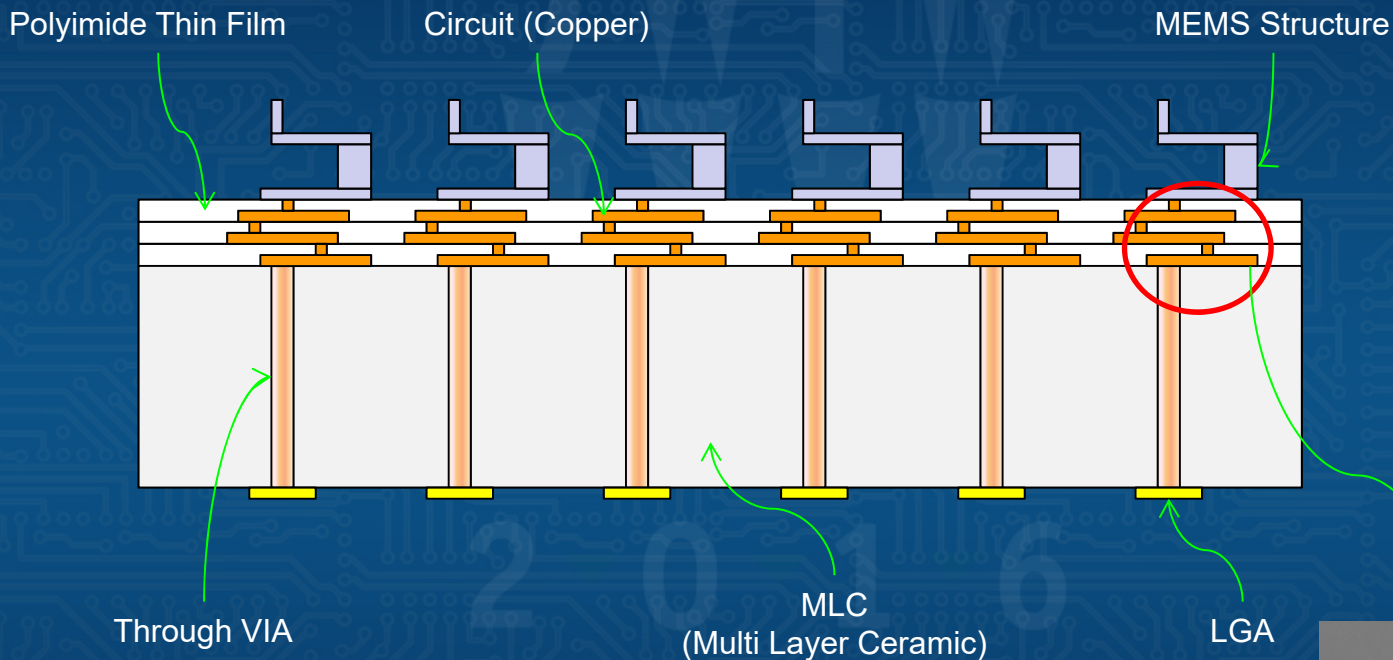
Basic Study for PI Circuit Design

- **Measurement (Insertion Loss)**
 - Analysis of Circuit Trace on Polyimide Thin Film



Signal Integrity on Probe Card

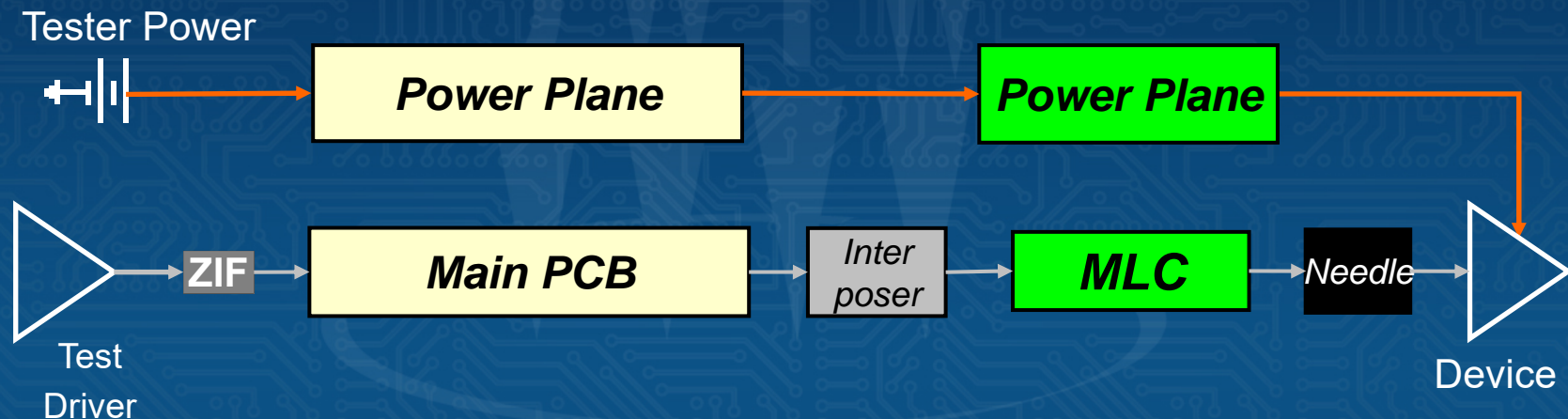
- **Concept of Circuit Design on Space Transformer (STF)**



- STF consists of Universal MLC and Polyimide Thin Film.
- Polyimide Circuit is made by MEMS Process.
- MEMS Structure is stacked up after Polyimide Circuit Process.

Signal Integrity on Probe Card

- **Simulation Conditions for Probe Card**

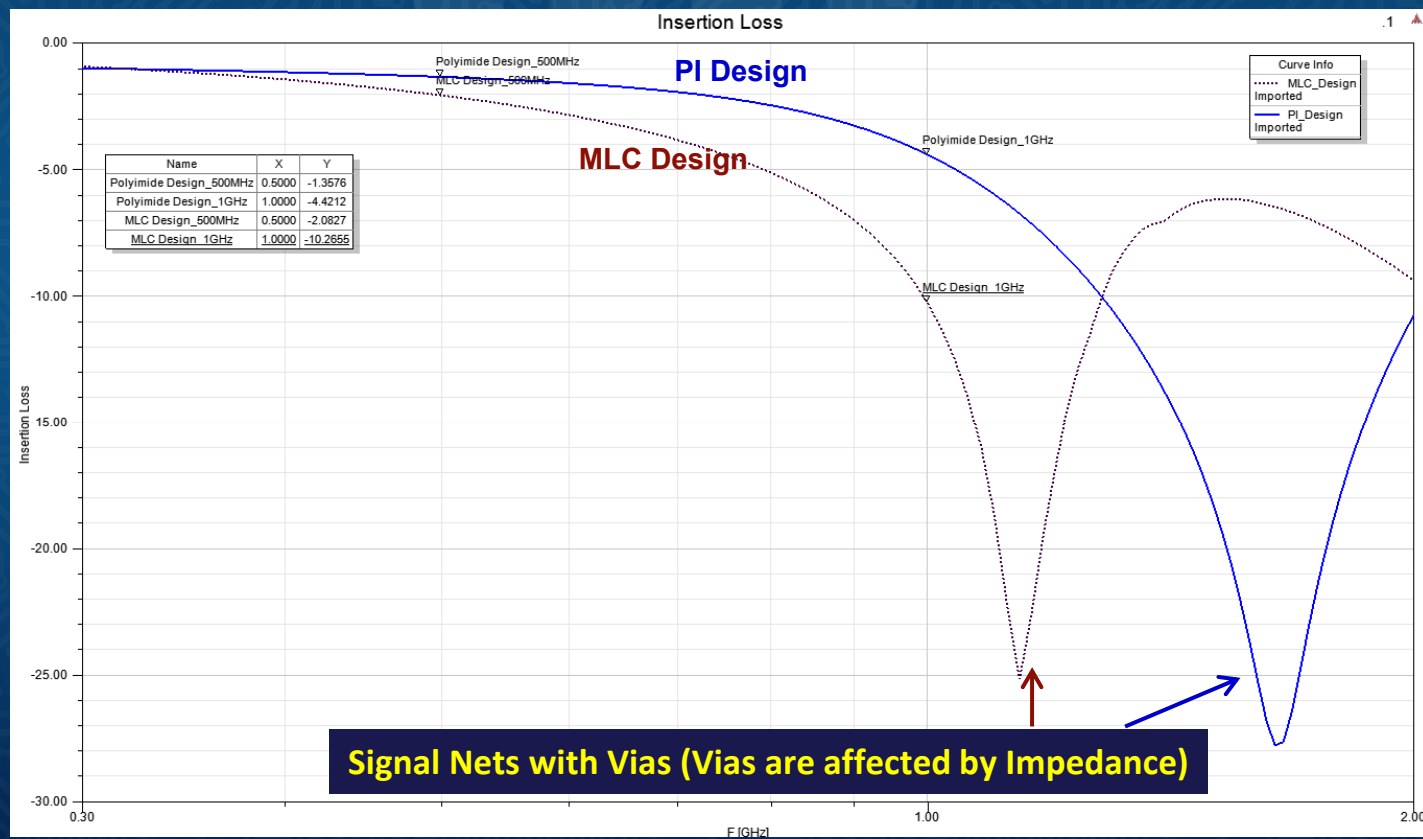


- Input Voltage : 1.1V
- Data : IO Ch.@Memory
- Data Rate : 100Mbps~1000Mbps (50MHz~500MHz)
- Factors : MLC Design vs PI Design on Probe Card
- Simulation Tool : SI Designer @ ANSYS

Signal Integrity on Probe Card

- **Insertion Loss (Simulation)**

- Analysis of MLC Circuit Design vs PI Circuit Design on Probe Card
- MLC Circuit Design -2.08dB vs PI Circuit Design -1.35dB@500MHz

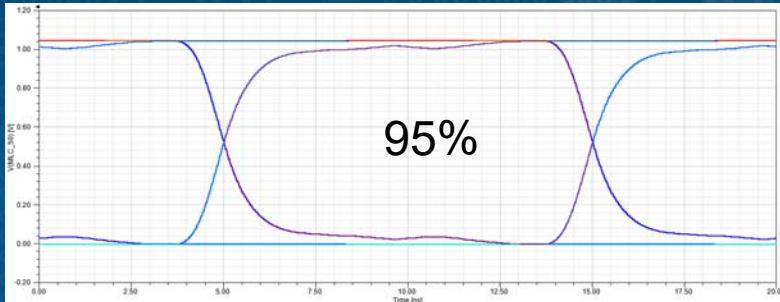


Signal Integrity on Probe Card

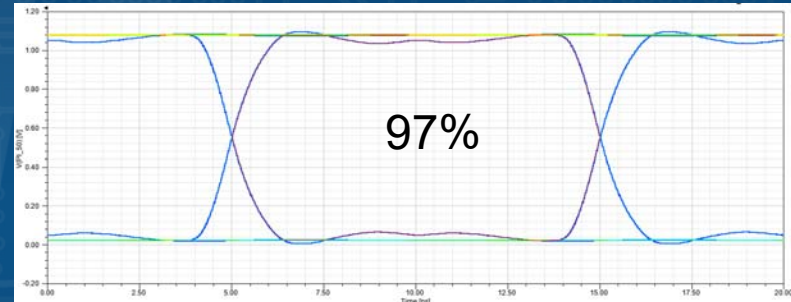
- **Eye Diagram (Simulation)**

- Analysis of MLC Circuit Design vs PI Circuit Design on Probe Card
- Eye-Opening : 95%~97%@50MHz, 93%~95%@100MHz

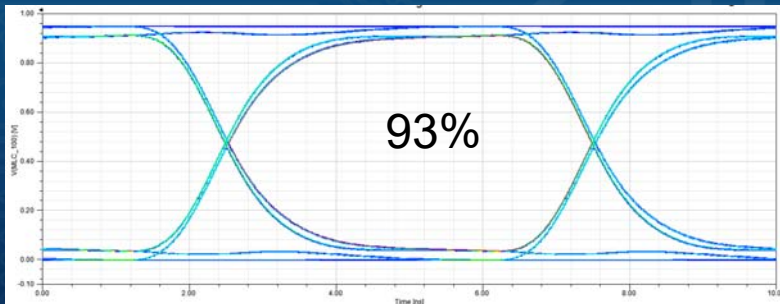
MLC Design : 50 MHz



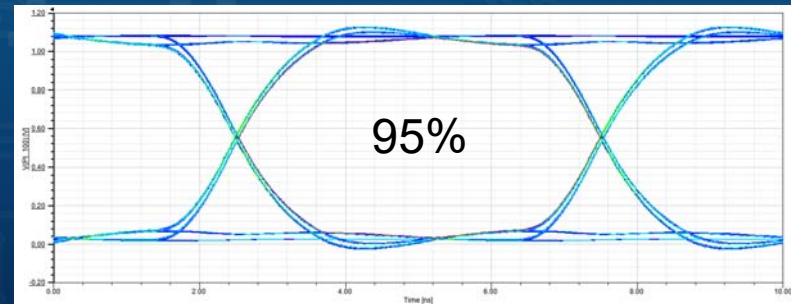
PI Design : 50 MHz



MLC Design : 100 MHz



PI Design : 100MHz



Signal Integrity on Probe Card

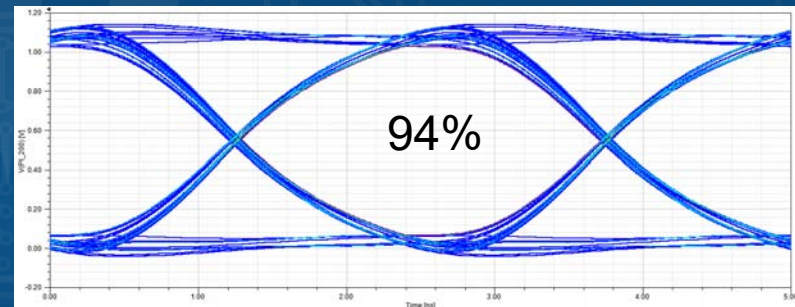
- **Eye Diagram (Simulation)**

- Analysis of MLC Circuit Design vs PI Circuit Design on Probe Card
- Eye-Opening : 90%~94%@200MHz, 51%~61%@500MHz

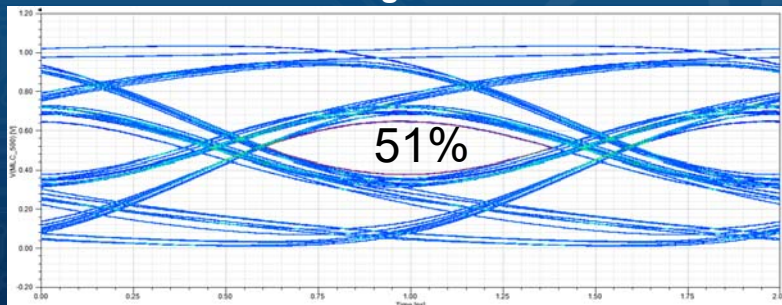
MLC Design : 200 MHz



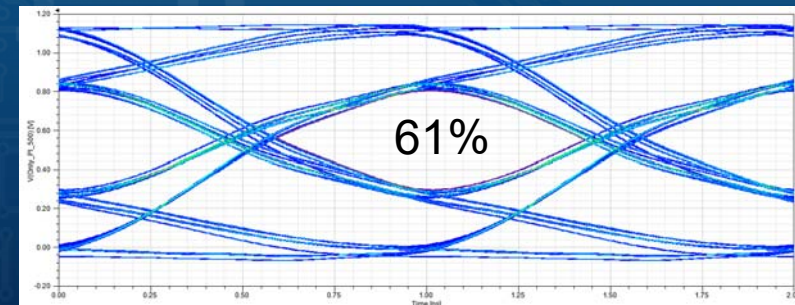
PI Design : 200 MHz



MLC Design : 500 MHz



PI Design : 500 MHz



Summary

- Basic Study for Polyimide Circuit Design was Performed and its Electrical Characteristics have been checked.
- Impedance of Circuit Design using Polyimide Thin Film can be Controlled by changing Trace Geometry.
- Signal integrity was analyzed using two kinds of Design Concept on Probe Card.

Future Works

- The Electrical Characteristics for Power integrity on Probe Card
 - Analysis of Power impedance using Polyimide Thin Film
 - Analysis of Effect for Decoupling Capacitor
 - Analysis of Power Noise as Ground Type(Mesh & Plane)

Acknowledgements



- Sang-Kyu Yoo
- Joon-Yoon Kim



- Yong-Ho Cho
- Sung-Mo Kang



- Jong-Kwan Yook

Thanks for Your Attention !

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